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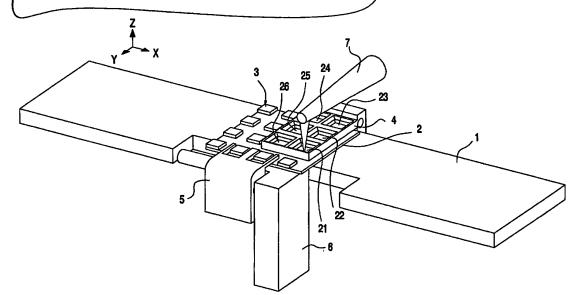
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(54) Title: WIREBONDING METHOD AND APPARATUS



(57) Abstract: A method and apparatus are discloses for wirebonding leads of a plurality of lead frames being part of a lead frame assembly by a wirebonding tool to semiconductor products mounted on the respective lead frames. The semiconductor products are clamped by a clamping mechanism comprising a stationary clamp and a movable clamp. The movable clamp follows the indexing movement of the lead frame assembly during wirebonding of the semiconductor products clamped by the movable clamp. The wirebonding process does not need to be interrupted for the indexing.

WO 2004/055870 A1



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